

ABSTRACT

A surface laminar circuit board includes an insulating layer, and a signal ground
conductive layer disposed on an upper surface of the insulating layer. The conductive
layer has a hole formed therein. A photosensitive dielectric layer is disposed on an
5 upper surface of the signal ground conductive layer. The dielectric layer has a photo
micro-via formed therein. A signal trace is disposed on the photosensitive dielectric
layer, and is electrically coupled with the signal ground conductive layer by way of the
photo micro-via. A conductive pad is provided, which has a majority thereof within an
area defined by an outer periphery of the hole. The conductive pad is electrically
10 coupled with the signal trace. A surface mounted component is mounted on the
conductive pad.